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October 2014

FDMS86252L

N-Channel Shielded Gate PowerTrench[®] MOSFET 150 V, 12 A, 56 m Ω

Features

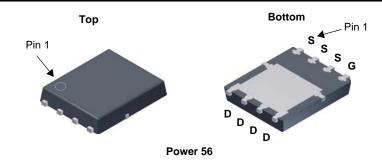
- Shielded Gate MOSFET Technology
- Max $r_{DS(on)} = 56 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 4.4 \text{ A}$
- Max $r_{DS(on)} = 71 \text{ m}\Omega$ at $V_{GS} = 6 \text{ V}$, $I_D = 3.8 \text{ A}$
- Max $r_{DS(on)} = 75 \text{ m}\Omega$ at $V_{GS} = 4.5 \text{ V}$, $I_D = 3.7 \text{ A}$
- Advanced package and silicon combination for low r_{DS(on)} and high efficiency
- Next generation enhanced body diode technology, engineered for soft recovery
- MSL1 robust package design
- 100% UIL tested
- RoHS Compliant

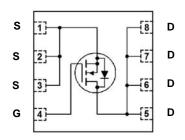
General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that incorporates Shielded Gate technology. This process has been optimized for the on-state resistance and yet maintain superior switching performance.

Applications

- OringFET / Load Switching
- Synchronous Rectification
- DC-DC Conversion





MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parame		Ratings	Units	
V_{DS}	Drain to Source Voltage			150	V
V_{GS}	Gate to Source Voltage			±20	V
	Drain Current -Continuous	T _C = 25 °C		12	
I _D	-Continuous	T _A = 25 °C	(Note 1a)	4.4	Α
	-Pulsed		(Note 4)	30	
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	73	mJ
D	Power Dissipation	T _C = 25 °C		50	W
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1a)	2.5	VV
T _J , T _{STG}	Operating and Storage Junction Tempera	ture Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	2.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS86252L	FDMS86252L	Power 56	13 "	12 mm	3000 units

Electrical Characteristics T_J = 25 °C unless otherwise noted Parameter

Off Characteristics									
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	150			V			
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		104		mV/°C			
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 120 V, V _{GS} = 0 V			1	μΑ			
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA			

Test Conditions

Min

Тур

Max

Units

On Characteristics

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	1	1.5	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250 \mu A$, referenced to 25 °C		-6		mV/°C
		V _{GS} = 10 V, I _D = 4.4 A		46	56	
		$V_{GS} = 6 \text{ V}, I_D = 3.8 \text{ A}$		48	71	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 3.7 \text{ A}$		52	75	mΩ
		$V_{GS} = 10 \text{ V, } I_{D} = 4.4 \text{ A,}$ $T_{J} = 125 ^{\circ}\text{C}$		90	110	
9 _{FS}	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 4.4 \text{ A}$		21		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 75 V V 0 V		952	1335	pF
C _{oss}	Output Capacitance	$V_{DS} = 75 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz		74	105	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1011 12		3	5	pF
R_g	Gate Resistance		0.1	0.6	1.8	Ω

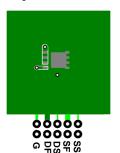
Switching Characteristics

t _{d(on)}	Turn-On Delay Time		6.8	14	ns
t _r	Rise Time	$V_{DD} = 75 \text{ V, } I_{D} = 4.4 \text{ A,}$	1.4	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	19	34	ns
t _f	Fall Time		2.9	10	ns
Qg	Total Gate Charge	V _{GS} = 0 V to 10 V	15	21	nC
Qg	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 75 \text{ V}$	7.6	11	nC
Q _{gs}	Gate to Source Charge	I _D = 4.4 A	2.1		nC
Q_{gd}	Gate to Drain "Miller" Charge		2.3		nC

Drain-Source Diode Characteristics

V_{SD}	1Source-Drain Dioge Forward voltage	$V_{GS} = 0 \text{ V, } I_S = 1.9 \text{ A}$ (Note 2)	0	.7	1.2	V
		$V_{GS} = 0 \text{ V}, I_S = 4.4 \text{ A}$ (Note 2)	0	.8	1.3	
t _{rr}	Reverse Recovery Time	-I _E = 4.4 A, di/dt = 100 A/μs	5	3	85	ns
Q _{rr}	Reverse Recovery Charge	1F = 4.4 A, di/dt = 100 A/μS	5	1	82	nC

^{1.} R_{0JA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0JC} is guaranteed by design while R_{0CA} is determined by the user's board design.



a. 50 °C/W when mounted on a 1 in² pad of 2 oz copper



b. 125 °C/W when mounted on a minimum pad of 2 oz copper.

- 2. Pulse Test: Pulse Width < 300 $\mu\text{s},$ Duty cycle < 2.0%.
- 3. E_{AS} of 73 mJ is based on Starting $T_J = 25$ °C, L = 3 mH, $I_{AS} = 7$ A, $V_{DD} = 150$ V, $V_{GS} = 10$ V. 100% tested at L = 0.1 mH, $I_{AS} = 24$ A.
- 4. Pulsed Id limited by junction temperature, td<=100 μ S, please refer to SOA curve for more details.

Typical Characteristics T_J = 25 °C unless otherwise noted

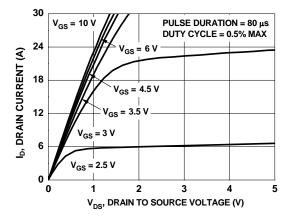


Figure 1. On Region Characteristics

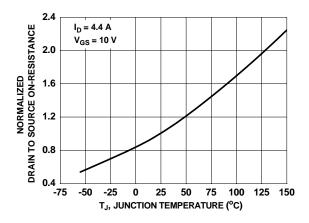


Figure 3. Normalized On Resistance vs Junction Temperature

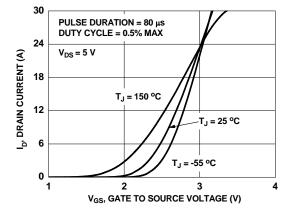


Figure 5. Transfer Characteristics

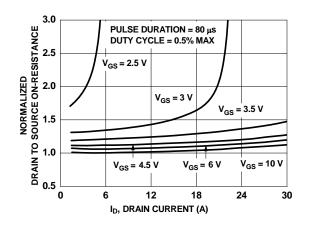


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

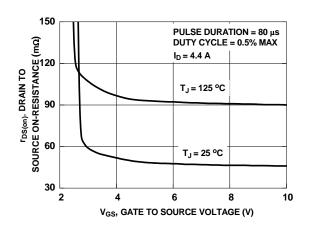


Figure 4. On-Resistance vs Gate to Source Voltage

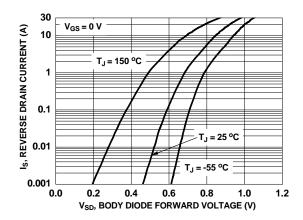


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

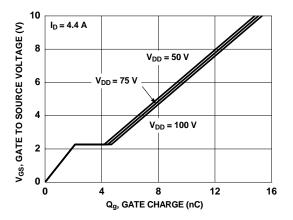


Figure 7. Gate Charge Characteristics

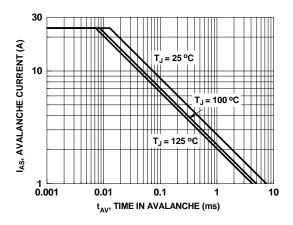


Figure 9. Unclamped Inductive Switching Capability

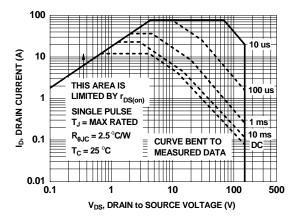


Figure 11. Forward Bias Safe Operating Area

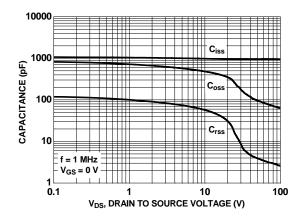


Figure 8. Capacitance vs Drain to Source Voltage

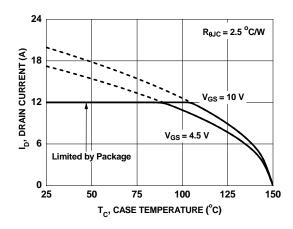


Figure 10. Maximum Continuous Drain Current vs Case Temperature

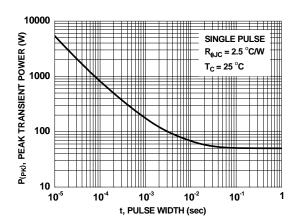


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25 °C unless otherwise noted

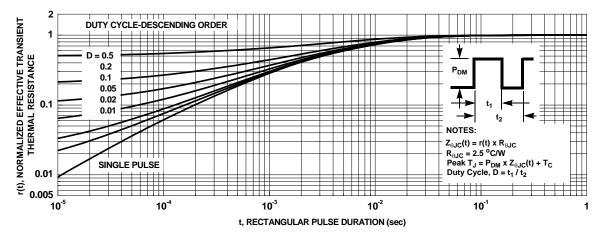


Figure 13. Junction-to-Case Transient Thermal Response Curve



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